



**TECHSPRAY**  
R E N E W™

*High Performance Eco-Cleaning™*

Product Information

**ECO-OVEN™**  
**SMT Oven Cleaner**  
**1573 (replaces 1691)**

Introduction



Cleans reflow ovens, wave soldering systems, and associated heat exchanger systems by removing all types of flux residues (e.g. water-based, RMA, no-clean, lead-free). Used for periodic preventative maintenance to keep equipment running at top levels. It is fast acting and more effective than IPA for baked-on flux residues.

One gallon container (1573-G) recommended for wave solder finger cleaning. Just pour into the designated reservoir of your wave soldering machine. Trigger pump on quart (1573-QT) eliminates the need for propellants, which can have a global warming impact.

One quart (with a trigger sprayer) and one gallon containers are ideal for surface and tool cleaning. Packaging is selected to be easily recyclable. Labels made of recycled paper, and cartons made of 40% recycled material.

Eco-Oven™ Cleaner is fully compliant with CARB (California Air Resource Board) requirements.

Also compliant with European REACH (Registration, Evaluation, Authorization & Restriction of Chemicals) and WEEE (Waste Electrical and Electronic Equipment Directive) initiatives. It does not contain RoHS (Restriction of Hazardous Substances) restricted substances, SVHC (Substances of Very High Concern) list substances, nor halides.

Features / Benefits

- Quickly Clean Flux Residue From Oven & Wave Fingers
- Safe On Warm Ovens
- Non-Flammable
- Biodegradable
- Low VOC
- Non-Ozone Depleting

Applications

- For removal of baked-on flux residues from SMT oven and wave solder equipment.
- Recommended for usage in all brands of wave solder equipment.
- Used for periodic preventive maintenance of SMT ovens and wave solder equipment.
- Avoid use on areas with aluminum, copper, brass, carbon steel, and galvanized steel.

<b>Application</b>	<b>Suggestions</b>
Oven cleaning	Reapply as necessary
Pallet cleaning	Let soak
Finger cleaning	Cycle wave with flux off to initially clean thick residues
Defluxing	Need to rinse. Read TDS for metal incompatibilities.

## About TECHSPRAY RENEW™

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**TECHSPRAY RENEW™** is a brand that represents **High Performance Eco-Cleaning™**. Techspray® has applied our expertise in solvent cleaning to formulate some of the most effective eco-friendly cleaners on the market. Performance is our top priority, using the best "green" solutions as they become available. We all are at the cusp of the ongoing movement toward sustainable products, packaging, and processes. It is Techspray's intention to stay at the cutting-edge while keeping our products powerful and cost effective.

## Directions

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### SMT Oven Cleaning

- Allow oven to cool down slightly and apply on warm surface (below 100°C).
- Spray and saturate the soiled area. Let soak for 5 minutes.
- Using a lint-free wipe (we recommend Techspray 2350-100 Wiper), wipe lightly at first to allow cleaning agent to break down residues.
- Continue to wipe in a circular motion until the flux residues are fully removed.
- Wipe completely with damp (w/water) cloth to remove remaining residue.
- Dispose of soiled wipe as appropriate depending on the type of residues removed.

### Wave Solder Finger Cleaning

- Fill cleaner into finger cleaning reservoir.
- Keep adequate liquid level.

## Chemical Components

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<u>Component</u>	<u>CAS#</u>
Ethanol, 2-amino- .....	141-43-5

*Includes other hazardous components in non-reportable quantities.*

## Chemical Properties (MSDS available on request)

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- EXPOSURE LIMIT: Manufacturer's recommendation 1000 ppm.
- PHYSICAL STATE: Liquid
- ODOR: Faint ethereal odor
- APPEARANCE: Clear, mobile liquid
- pH: 10-11
- PERCENT VOLATILE: 90% at 104°C
- VAPOR PRESSURE: < 0.02 mmHg@20°C (VOC Composite Vapor Pressure)
- BOILING POINT : ~212°F (100°C)
- FLASHPOINT AND METHOD (TAG Closed Cup): None
- SOLUBILITY IN WATER: Fully miscible
- DENSITY: 1.00 at 25°C
- VOC (by wt): 2.2%, 21.8 g/l

## Performance

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*Tested according to modified MIL-PRF-29608 4.59 standards:*

*Fluxed coupons cured for 15 minutes at 212°F (100°C).*

*Flux is applied to cleaning coupons, cured, sprayed with cleaning fluid, allowed to sit 10-seconds, then a poly-cellulose wipe (saturated with same cleaning fluid) is dragged across one time using a dowel to maintain consistent pressure.*

*Percentage refers to the amount of soil (by weight) removed from stainless steel test coupon.*

	R-100	No-Clean	Water-Soluable
<b>Techspray Renew Eco-Oven Cleaner 1573</b>	<b>94%</b>	59%	<b>96%</b>
99.8% IPA	<b>96%</b>	<b>70%</b>	82%
Techspray Water-Based SMT Oven Cleaner 1691	84%	26%	73%

## Compatibility

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### Metals

*Test method: 24 hour submersion in sealed container.*

<b>Material</b>	<b>Compatibility</b>
<b>Brass foil</b>	Not recommended
<b>Copper foil</b>	Not recommended
<b>Nickel 200</b>	Excellent
<b>Aluminum 6061</b>	Not recommended
<b>Aluminum 2024</b>	Not recommended
<b>Anodized aluminum</b>	Not recommended
<b>Stainless Steel 316</b>	Excellent
<b>Stainless Steel 304</b>	Excellent
<b>Mild carbon steel</b>	Not recommended
<b>Galvanized Steel</b>	Not recommended

*Note: Eco-Oven™ is a water-based formula, so will encourage oxidation with prolonged exposure to iron, steel, and other susceptible metals.*

## Environmental Policy

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Techspray® is committed to developing products to ensure a safer and cleaner environment. We will continue to meet and sustain the regulations of all federal, state and local government agencies.